Ground-Bounce Reduction in Narrow-Band RF Front-Ends



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Outline

- Ground-bounce in RFICs
 - Effect on impedance-matching and stability
- Reducing ground-bounce in narrowband RF circuits
- Reducing PA sensitivity to switching noise
- Summary

Motivation for this work

Ground-bounce in RFICs



Matching



Stability



PA ground bounce reduction

Reducing ground-bounce (conventional)

- Minimize bond-wire inductance
 - Multiple bond-wires in parallel
 - Reducing bond-wire length by placing die at an offset from centre
- Differential implementation
- On chip supply decoupling capacitor

Reducing ground-bounce (proposed)



Stabilization



Simulation – series resonance



- 2.5GHz PA with 16dBm P1dB in 130nm CMOS
- Bond-wire: 2nH, Q=100 (worst-case)

Simulation – Input matching





PA sensitivity to switching noise

Effect of switching noise



Current drawn by onchip circuitry causes ground bounce

> **Desired**: Full signal current I_s through load while isolating from I_n

Impedance balance



Simulation – switching noise



- Same PA as before
- Three inverters to generate switching noise
- Impedance balanced at PA o/p using two tanks
- Series cap to prevent dc short between rails

Simulation – output noise



Summary

 Significant ground-bounce reduction is possible in narrow-band RF front-ends using the proposed series-resonance technique

- Uses extra ground pin and one external capacitor

 Impedance balance in output stage can suppress noise added by on-chip circuitry

Thank You

Questions?